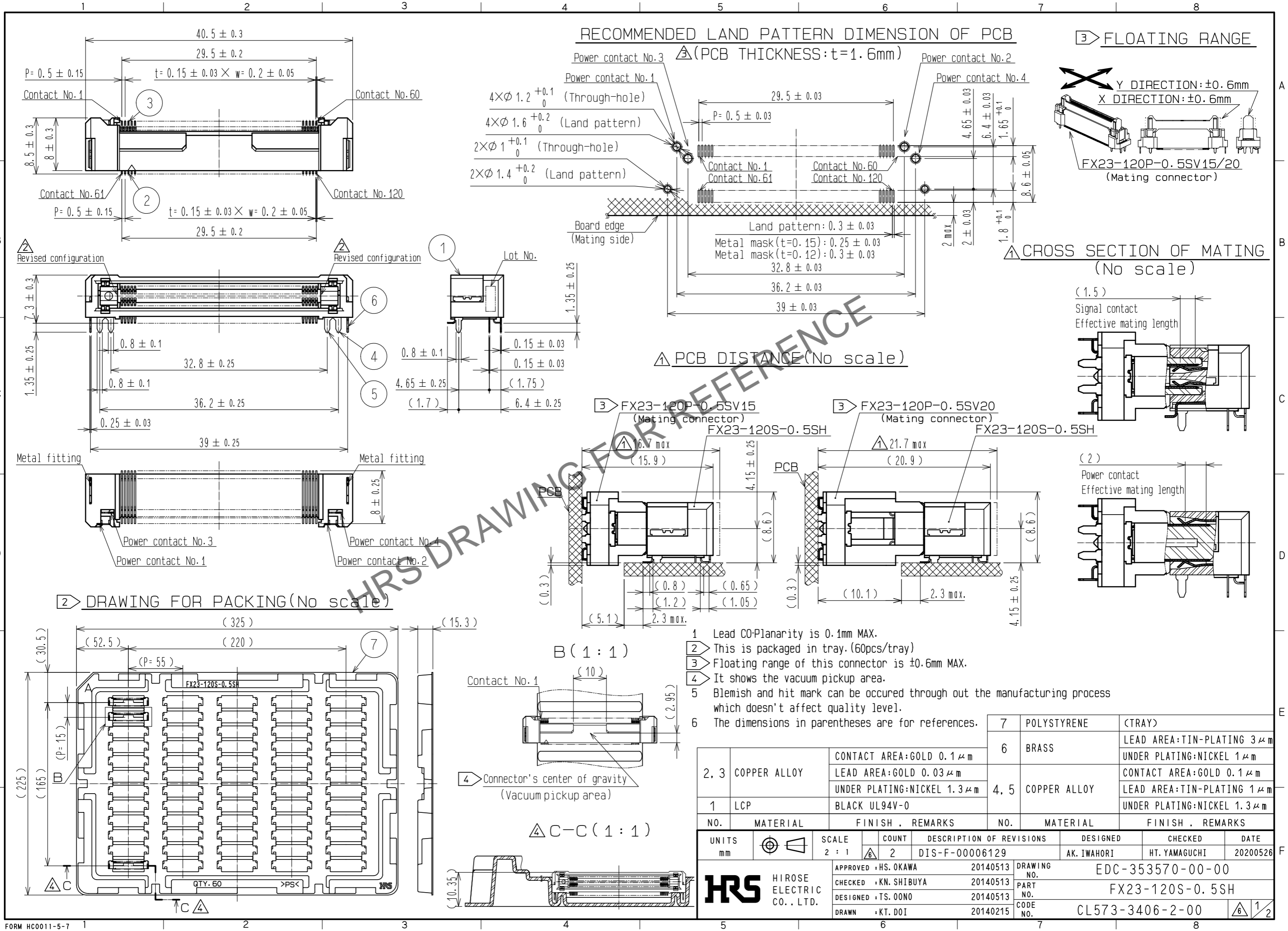
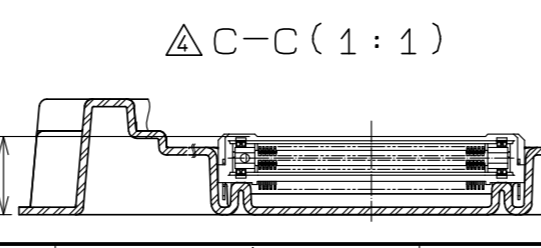
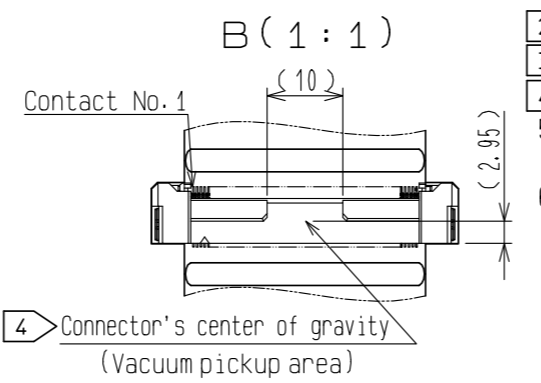
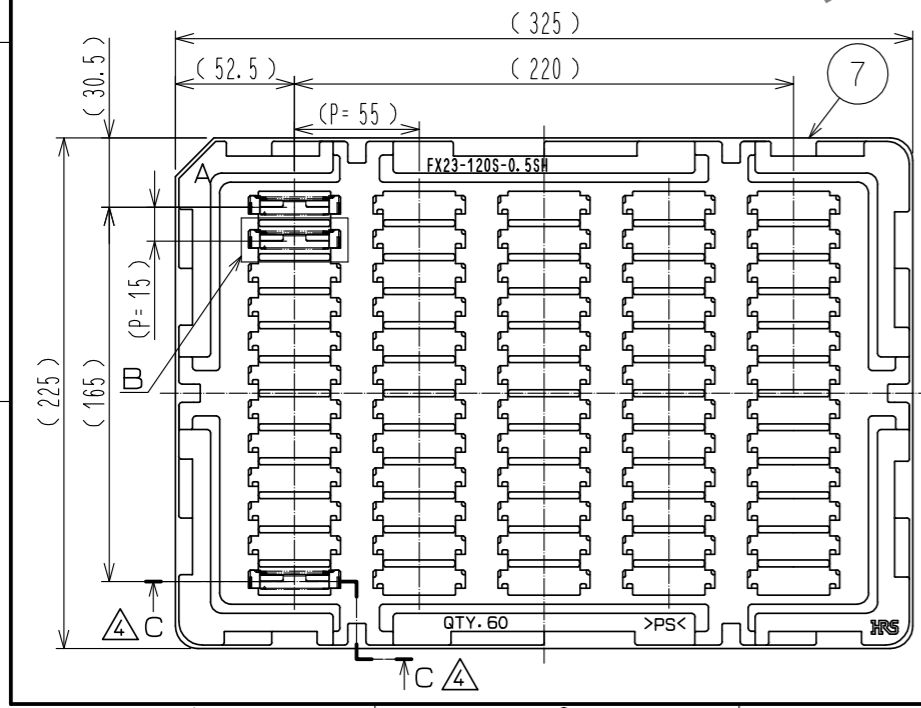


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2 DRAWING FOR PACKING (No scale)



NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
2, 3	COPPER ALLOY		CONTACT AREA: GOLD 0.1 μm LEAD AREA: GOLD 0.03 μm UNDER PLATING: NICKEL 1.3 μm	7	POLYSTYRENE		(TRAY)
1	LCP		BLACK UL94V-0	6	BRASS		LEAD AREA: TIN-PLATING 3 μm UNDER PLATING: NICKEL 1 μm
				4, 5	COPPER ALLOY		CONTACT AREA: GOLD 0.1 μm LEAD AREA: TIN-PLATING 1 μm UNDER PLATING: NICKEL 1.3 μm

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2:1	2	DIS-F-00006129	AK. IWAHORI	HT. YAMAGUCHI	20200526

APPROVED	CHECKED	DESIGNED	DRAWN	DRAWING NO.	PART NO.	CODE NO.
HS. OKAWA	KN. SHIBUYA	TS. OONO	KT. DOI	20140513	20140513	20140215

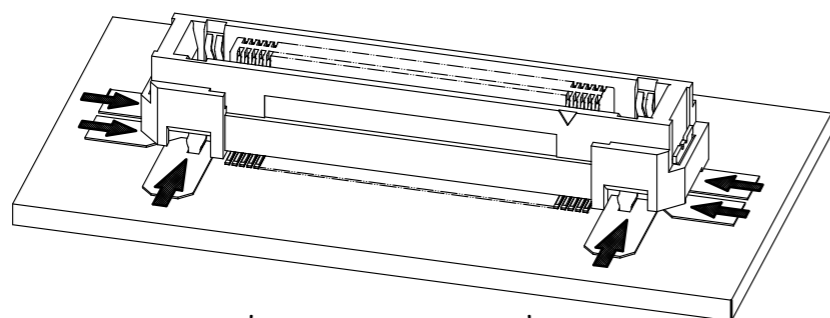
DRAWING NO.	PART NO.	CODE NO.
EDC-353570-00-00	FX23-120S-0.5SH	CL573-3406-2-00

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In order to prevent any potential failures with the connector, please read the following below:

[Through Hole Reflow Process]

FX23 and FX23L Series use through hole reflow process, where power contacts/metal fittings draw solder paste from the surrounding area. In regards to the soldering paste print area, the surface shall be flat with no exposed copper surface. If the surface is not flat, power contacts/metal fittings may not properly draw the soldering paste, resulting insufficient solder on the power contacts/metal fittings as well as ball-shaped solder on the PCB.

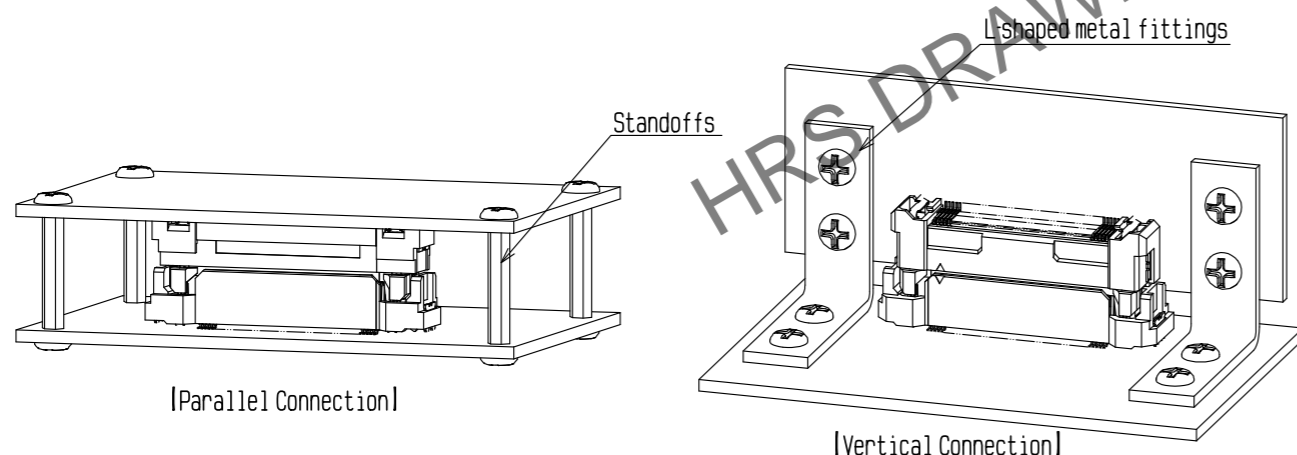


[Through Hole Reflow Image]

When applying solder from the opposite side of the PCB, due to the unavailability in solder space on the mounting side, there may be a case where solder is insufficiently applied to power contacts/metal fittings. Please check if the power contacts/metal fittings are properly soldered when doing so.

[Board Stabilization]

This connector can absorb misalignment of boards but cannot absorb vibration itself. When boards are supported by a connector only, the connector will be loaded excessively, which may result in a damage or contact failure. Take measures to secure boards with an object other than connector as shown in the following figure.



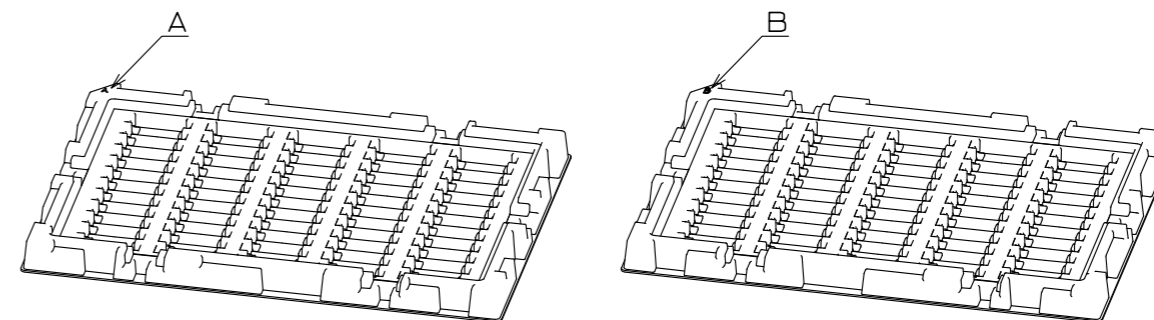
[Parallel Connection]

[Vertical Connection]

Note that when a spacer is installed far from connectors, incomplete mating of the connectors may occur due to sagging of the board, etc. Mate connectors surely and then fix a spacer.

[When Storing with Tray Packaging]

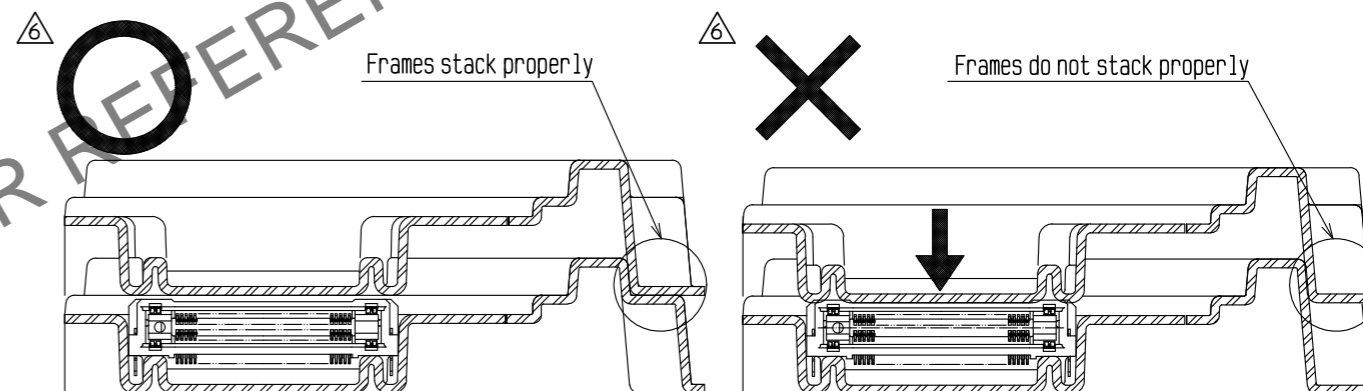
Please be cautious when stacking trays when storing. There are two types of trays (tray A, tray B), and designed to stack alternately.



[Tray A]

[Tray B]

If tray A is stacked to another tray A or tray B is stacked to another tray B, load may be applied to the connector, causing the deformation or breakage of the connector.



Frames stack properly

Frames do not stack properly

If the tray is stacked correctly, tray's frame prevents from upper tray applying force to the connector on bottom tray.

If same type of tray is stacked on top of each other, load will be directly applied to the connector.

When storing, please stack the trays alternatively (tray A, tray B, tray A, tray B, tray A....)

[In Regards to Design Guideline]

To provide more information in regards to the usage of this product, we have prepared a detailed manual (ETAD-F0887-00). Please contact our sales representative if needed.

Added the second page.

HRS	DRAWING NO.	EDC-353570-00-00		2/2
	PART NO.	FX23-120S-0.5SH		
	CODE NO.	CL573-3406-2-00		